Product/Process Change Notice - PCN 20_0025 Rev. -

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This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

PCN Title: ADG1411WBCPZ-REEL Assembly Site Transfer and Datasheet Specification Changes.

Publication Date: 18-Feb-2020

Effectivity Date: 22-May-2020 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:
Initial Release

Description Of Change:

The ADG1411WBCPZ-REEL Assembly location will change from Amkor Phillippines(AP3) to ASE Korea(AEK).

The following Datasheet Specifications changes are occurring.
Changes to +25C specs: (All Supplies)
Source Off Leakage,Is(Off) specification is changing from +/-0.55na to +/-3.0na.
Drain Off Leakage,Id(Off) specification is changing from +/-0.55na to +/-3.0na.

Changes to +25C specs:
Channel On Leakage,Id, Is(On) specification is changing from +/-1.0na to +/-3.0na. (+/-5V Dual Supply)
Channel On Leakage,Id, Is(On) specification is changing from +/-1.5na to +/-3.0na. (+12V Single Supply)
Channel On Leakage,Id, Is(On) specification is changing from +/-2.0na to +/-3.0na. (+/-15V Dual Supply)

Changes from -40C to +125C specs: (All Supplies)
Source Off Leakage,Is(Off) specification is changing from +/-12.5na to +/-40na.
Drain Off Leakage,Id(Off) specification is changing from +/-12.5na to +/-40na.
Channel On Leakage,Id, Is(On) specification is changing from +/-30na to +/-40na.

Reason For Change:

Assembly Site Transfer:
To align with ADI's Automotive manufacturing strategy. The use of AEK as an assembly site for this part will ensure continued source of product supply.

Datasheet Changes:
Specification updates are being done to more accurately reflect the device capability.

Impact of the change (positive or negative) on fit, form, function & reliability:

There is no impact on the form, fit, function and reliability of the part.

Product Identification *(this section will describe how to identify the changed material)*

Specification changes will be reflected in Rev D of the datasheet.
The changeover date code will be advised in a later revision of this PCN.

Summary of Supporting Information:

Qualification has been performed per AEC-Q100, Stress Test Qualification for Integrated Circuits. See attached Qualification Results Summary.

Supporting Documents

Attachment 1: Type: Delta Qualification Matrix

ADI_PCN_20_0025_Rev_-_ADG1411_Delta Qualification_ Matrix.xlsx

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Attachment 2: Type: Qualification Results Summary

ADI_PCN_20_0025_Rev_-_Qual Results Summary for PCN 20_0025.docx

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.			
Americas: PCN_Americas@analog.com	**Europe:** PCN_Europe@analog.com	**Japan:** PCN_Japan@analog.com	**Rest of Asia:** PCN_ROA@analog.com

Appendix A - Affected ADI Models				
Added Parts On This Revision - Product Family / Model Number (1)				
ADG1411 / ADG1411WBCPZ-REEL				

Appendix B - Revision History			
Rev	**Publish Date**	**Effectivity Date**	**Rev Description**
Rev. -	18-Feb-2020	22-May-2020	Initial Release

Assembly Site Move & Datasheet Spec Changes for ADG1411WBCPZ-REEL

Qualification Results Summary of ADG1411WBCPZ-REEL

QUALIFICATION PLAN			
TEST	**SPECIFICATION**	**SAMPLE SIZE**	**RESULTS**
Electrostatic Discharge *Field-Induced Charged Device Model* (corner pins)	JEDEC *JS-002*	3/voltage	Pass ±750V
Electrostatic Discharge *Field-Induced Charged Device Model* (all pins)	JEDEC *JS-002*	3/voltage	Pass ±1250V
Electrostatic Discharge *Human Body Model*	JEDEC *JESD22-A114*	3/voltage	Pass ±4000V
Latch-Up	JEDEC *JESD78*	3/current	Pass ±200mA
Highly Accelerated Stress Test (HAST)[1]	JEDEC *JESD22-A110*	3 x 77	Pass
Unbiased Highly Accelerated Stress Test (uHAST)[1]	JEDEC *JESD22-A118*	3 x 77	Pass
High Temperature Operating Life (HTOL)[1]	JEDEC *JESD22-A108*	3 x 77	Pass
High Temperature Storage Life (HTS)	JEDEC *JESD22-A103*	1 x 45	Pass
Temperature Cycle Test (TCT)[1]	JEDEC *JESD22-A104*	3 x 77	Pass

Assembly Site Move & Datasheet Spec Changes for ADG1411WBCPZ-REEL

Wire Bond Pull[2]	MIL-STD-883 M2011	1 x 10	Pass
Solder Heat Resistance (SHR)[1]	JEDEC *J-STD-020*	3 x 16	Pass
Solderability	JEDEC *J-STD-002*	1 x 15	Pass

[1]Preconditioned per JEDEC J-STD-020 Level 3
[2]Post-TCT (Temperature Cycle Test)